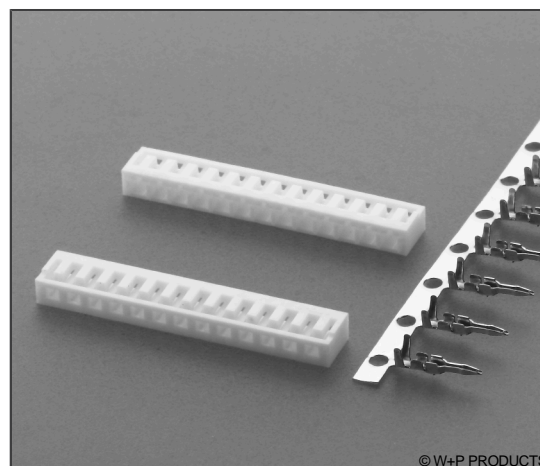


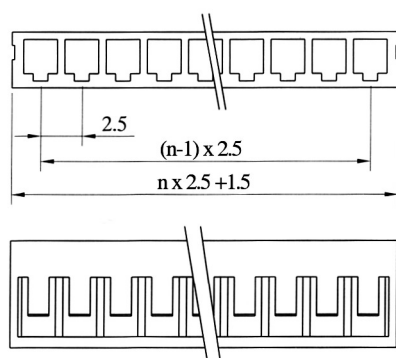
Crimp-Verbinder RM 2,50mm, gerade, Einlöt-Kontakte Crimp Connectors, 2.50mm Pitch, Straight, Solder-In Terminals

Technische Daten / Technical Data

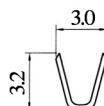
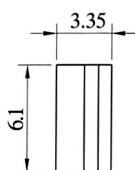
Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Aderquerschnitt <i>Applicable wire Gauge</i>	AWG 28 ~ 22 <i>AWG 28 ~ 22</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 800 MΩ <i>> 800 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	1 kV AC <i>1 kV AC</i>
Nennspannung <i>Voltage Rating</i>	250 V AC <i>250 V AC</i>
Nennstrom <i>Current Rating</i>	3 A <i>3 A</i>
Temperaturbereich <i>Temperature Range</i>	-25 °C ... +85 °C <i>-25 °C ... +85 °C</i>
Verarbeitung <i>Processing</i>	Wellenlötverfahren <i>Wave soldering</i>



© W+P PRODUCTS



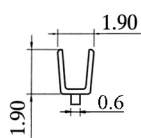
Housing



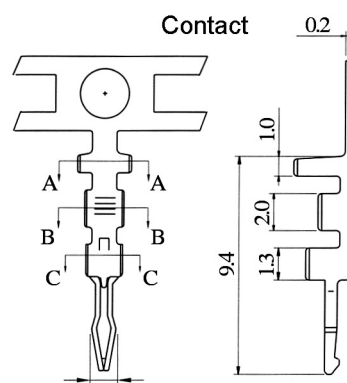
SEC A-A



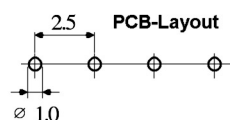
SEC B-B



SEC C-C



Contact



PCB-LAYOUT

Series

573

Contacts*

04

02-16

Type

1

1 Crimp-Gehäuse
Crimp housing

Series

573

Contacts

01

Type

2

2 Crimp-Kontakte
Crimp contacts

Plating

50

50 Verzinkt
Tin plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.

Empfohlenes Wellenlötprofil:

